## SN54ABTH16245, SN74ABTH16245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS662I - MARCH 1996 - REVISED MARCH 1999

- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- Distributed V<sub>CC</sub> and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB
- High-Drive Outputs (–32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- **Package Options Include Plastic Shrink** Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

#### description

The 'ABTH16245 devices are 16-bit noninverting external timing requirements.

3-state transceivers that provide synchronous two-way communication between data buses. The control-function implementation minimizes

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the devices so that the buses are effectively isolated.

When V<sub>CC</sub> is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH16245 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABTH16245 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SN54ABTH16245 . . . WD PACKAGE SN74ABTH16245...DGG, DGV, OR DL PACKAGE (TOP VIEW)

	$\overline{}$		_			
1DIR [	1	$\cup$	48	b	10E	
1B1 [			47	þ	1A1	
1B2	3		46	þ	1A2	
GND [	4		45		GND	
1B3	5		44		1A3	
1B4			43	_	1A4	
V <sub>CC</sub>			42	0	$V_{CC}$	
1B5			41		1A5	
1B6			40		1A6	
GND [	1				GND	
1B7			38		1A7	
1B8			37		1A8	
2B1			36		2A1	
2B2			35		2A2	
GND [			34		GND	
2B3			33		2A3	
2B4			32		2A4	
V <sub>CC</sub>	18		31	P	$V_{CC}$	
2B5					2A5	
2B6					2A6	
GND [					GND	
2B7					2A7	
2B8				_	2 <u>A8</u>	
2DIR [	24		25	Ц	2 <mark>OE</mark>	
				•		

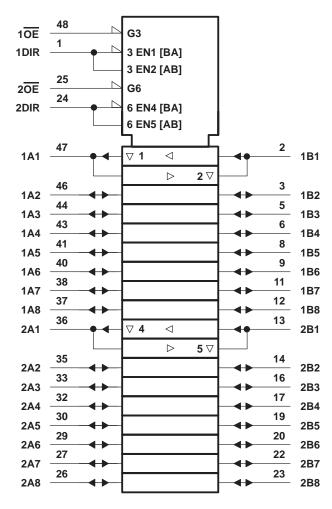
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#### **FUNCTION TABLE** (each 8-bit section)

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

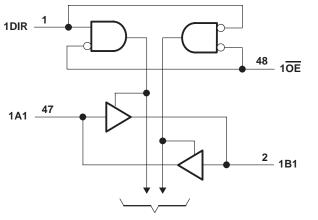
# logic symbol†

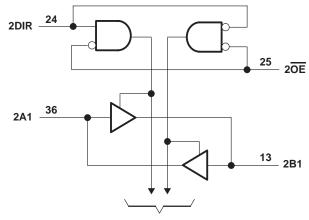


<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



## logic diagram (positive logic)





To Seven Other Channels To Seven Other Channels

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V <sub>O</sub>	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABTH16245	96 mA
SN74ABTH16245	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	−50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T <sub>stg</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

### recommended operating conditions (see Note 3)

			SN54ABTI	116245	SN74ABTI	H16245	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	VIH High-level input voltage				2		V
V <sub>IL</sub>	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	Vcc	V
ІОН	OH High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		<b>-</b> 55	125	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51.

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### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Т	A = 25°C	;	SN54ABTI	H16245	SN74ABTH16245		UNIT	
FAR	KAWIETEK	1231 00	RDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT	
٧ıK		V <sub>CC</sub> = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/-··		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		v	
VOH		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				V	
		VCC = 4.5 V	I <sub>OH</sub> = -32 mA	2*					2			
\/a.		V 45V	I <sub>OL</sub> = 48 mA			0.55		0.55			V	
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V	
V <sub>hys</sub>					100						mV	
l <sub>l</sub>	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = V <sub>CC</sub> or GND			±1		±1		±1	μА	
	A or B ports					±100		±100		±100		
1.0		V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 0.8 V	100			100		100		μА	
l(hold)	)	VCC = 4.5 V	V <sub>I</sub> = 2 V	-100			-100		-100			
		$V_{CC} = 0 \text{ to } 1.9 \text{ V}$	$V_{O} = 0.5 \text{ V to } 2.7 \text{ V},$			±50**		±50**			μА	
IOZPU	J	$V_{CC} = 0 \text{ to } 2.1 \text{ V}$	OE = X			±50				±50	μΑ	
		$V_{CC} = 1.9 \text{ V to } 0$	$V_0 = 0.5 \text{ V to } 2.7 \text{ V},$			±50**		±50**			μА	
IOZPD	)	$V_{CC} = 2.1 \text{ V to } 0$	OE = X			±50				±50	μΑ	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ	
IO <sup>‡</sup>		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	<b>-</b> 50	-180	-50	-180	mA	
		V <sub>CC</sub> = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports	$I_{O} = 0$ ,	Outputs low			32		32		32	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
		V <sub>CC</sub> = 5.5 V, One in Other inputs at V <sub>CC</sub>				1.5		1.5		1.5	mA	
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF	
C <sub>io</sub>	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			6						pF	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

<sup>\*\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

## SN54ABTH16245, SN74ABTH16245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

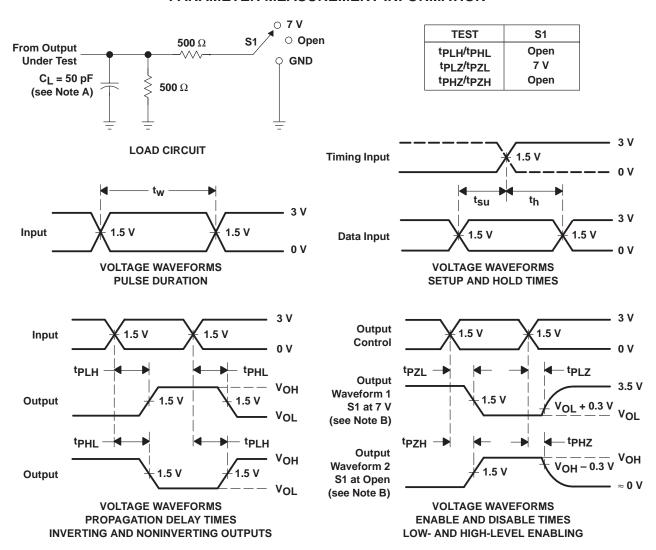
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V A = 25°C	', ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A or B	B or A	1	2.2	3.6	0.5	4.1	ns
<sup>t</sup> PHL	7010	BOIA	1	2.3	3.8	0.5	4.4	115
<sup>t</sup> PZH	ŌĒ	B or A	1	3.6	5.2	0.8	6.4	ns
t <sub>PZL</sub>	OE		1	3.7	6.1	0.9	6.5	115
<sup>t</sup> PHZ	ŌĒ	B or A	2	4.4	6.7	1.3	7.9	ns
<sup>t</sup> PLZ	UE		1.5	3.3	4.7	1.4	5.6	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A or B	B or A	1	2.2	3.4	1	3.9	ns
<sup>t</sup> PHL	AOIB	B OF A	1	2.3	3.7	1	4.2	115
<sup>t</sup> PZH	ŌĒ	B or A	1	3.6	5.2	1	6.3	20
tPZL	OE OE	D OI A	1	3.7	5.4	1	6.4	ns
t <sub>PHZ</sub>	ŌĒ	P or A	2	4.4	5.8	2	6.3	ns
t <sub>PLZ</sub>	UE UE	B or A	1.5	3.3	4.7	1.5	5.2	115

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50~\Omega$ ,  $t_f \leq$  2.5 ns.  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9762501QXA	ACTIVE	CFP	WD	48	1	TBD	A42 SNPB	N / A for Pkg Type
74ABTH16245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTH16245DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTH16245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH16245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH16245DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH16245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH16245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABTH16245WD	ACTIVE	CFP	WD	48	1	TBD	A42 SNPB	N / A for Pkg Type

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

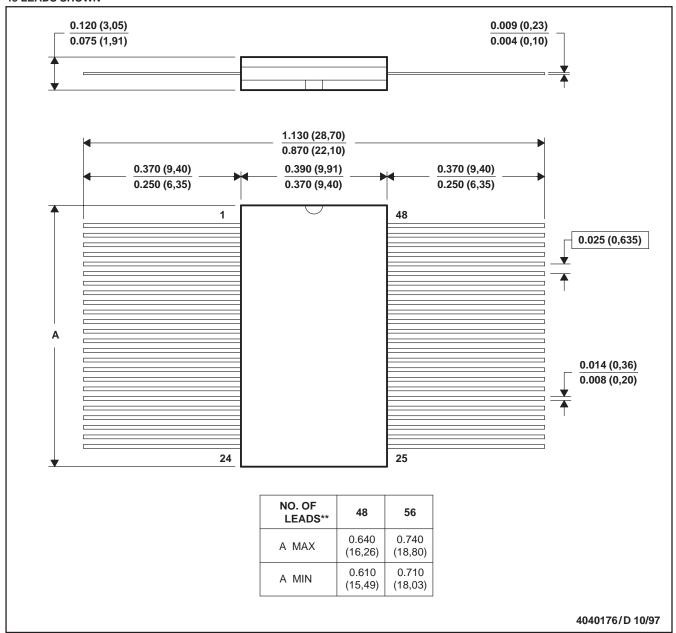
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### WD (R-GDFP-F\*\*)

#### **CERAMIC DUAL FLATPACK**

### **48 LEADS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

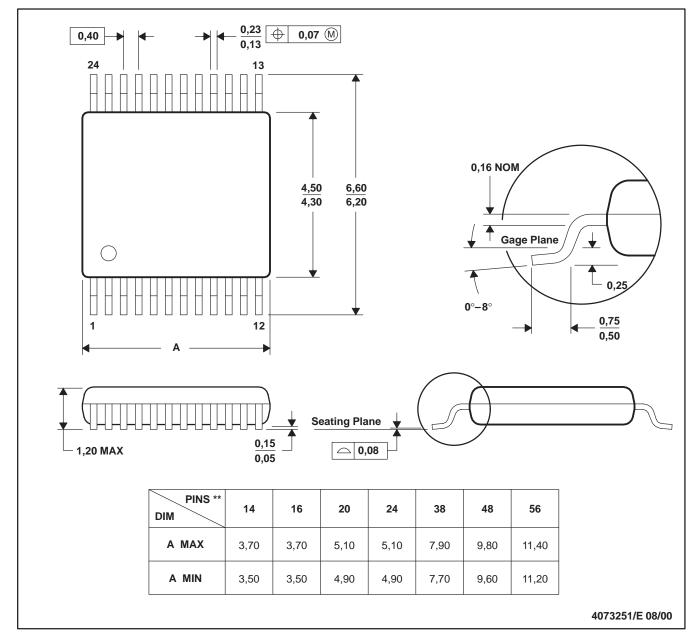
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

## DGV (R-PDSO-G\*\*)

### **24 PINS SHOWN**

### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

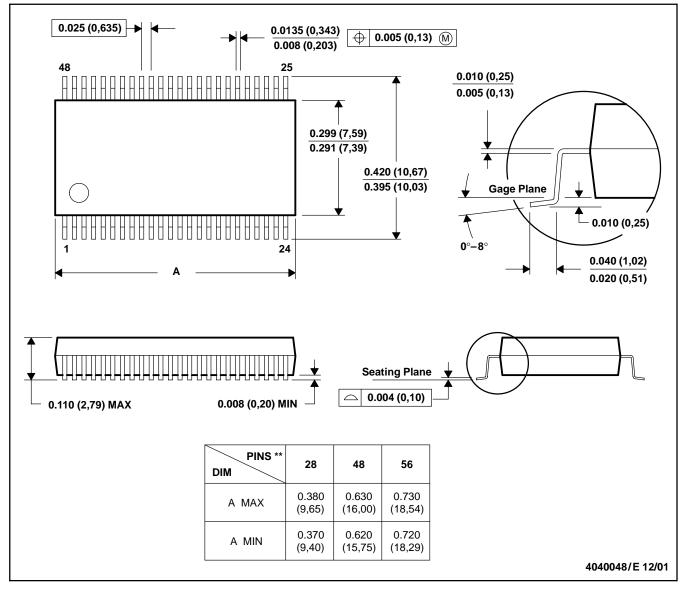
D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



### DL (R-PDSO-G\*\*)

### **48 PINS SHOWN**

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

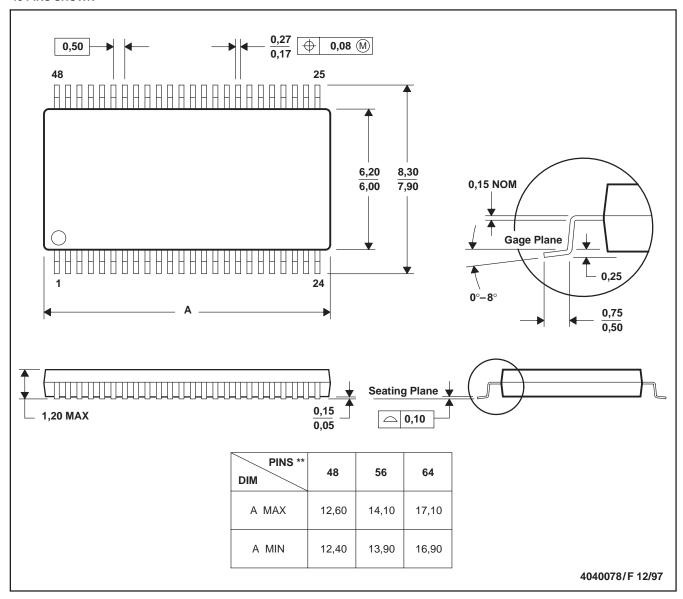
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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